



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Jong-Myoung Lee
Assignee: Samsung Electronics Co., Ltd.
Title: Lead On Chip Type Semiconductor Package
Serial No.: 09/710,606 Filing Date: November 18, 2000
Examiner: Nitin Parekh Group Art Unit: 2811
Docket No.: AB-1060 US

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Washington, D. C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

This is in response to the Office Action mailed February 1, 2002, which has a statutory shortened period for response that ended on May 1, 2002. The time allowed for this response has been extended to August 1, 2002, by the enclosed Petition and fee. Applicants respectfully request reconsideration in view of the following remarks and amendments that overcome the Examiner's rejections and objections.

IN THE CLAIMS

The following is a clean version of the entire set of pending claims. In accordance with 37 CFR § 1.121(c)(1)(ii), in attached "Version With Markings To Show Changes Made" provides marked up versions of the claims containing the newly introduced changes.

1. (Amended.) An LOC type semiconductor package, comprising:
a semiconductor chip on which a plurality of bonding pads are arranged in a row;

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